GPA-2634A

GaAs MMIC Power Amplifier Chip, 26-34GHz

Performance characteristics

Frequency range: 26-34GHz
Small Signal Gain: 25.5 dB
P-1dB: 33 dBm
Psat: 33.5 dBm
Power supply: + 6V@1300mA
50Ohm input/output
100% on-chip testing
Chip size: 2.6 x 2.44 x 0.1mm

Product Introduction

GPA -2634A is a broadband high-gain, high-efficiency, high- power amplifier chip based on GaAs technology , covering a frequency range of 26~34GHz, a small signal gain of 25.5dB, and a P-1 output power of 33dBm. The chip via metallization process ensures good grounding, and the back side is metallized for eutectic sintering process.

Use restriction parameter [1]	
Maximum drain voltage	+9 V
Maximum gate bias	- 3 V
Maximum input power	+25 dBm
Operating temperature	-55 ~ +85°C
Storage temperature	-65 ~ +150°C

【1】 Exceeding any of these maximum limits may cause permanent damage.

Electrical parameters (Ta=+25°C, Vd= 6 V, Vg=-0.8V, Ids= 1300 mA)				
index	Minimum	Typical Value	Maximum	unit
Frequency Range		26-34		GHz
Small Signal Gain	25	25.5	27.5	dB
Gain Flatness		± 1.25		dB
P-1dB	32.5	33	34	dBm
Psat	33	33.5	34	dBm
OIP3@30G with 24dBm/tone		35.5		dBm
Input return loss	8	14	-	dB
Output return loss	8	11	-	dB
* By tuning the Vg terminal voltage -2V~0V , the recommended gate voltage is -0.8V.				

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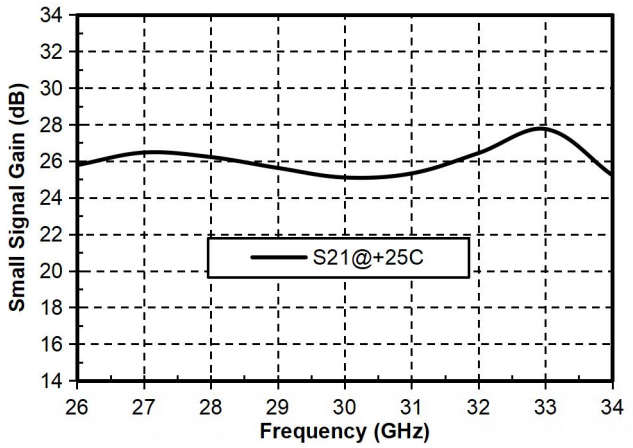
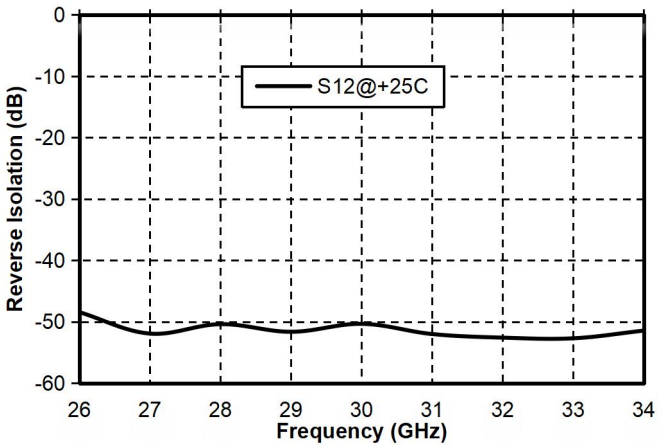
Main index test curve

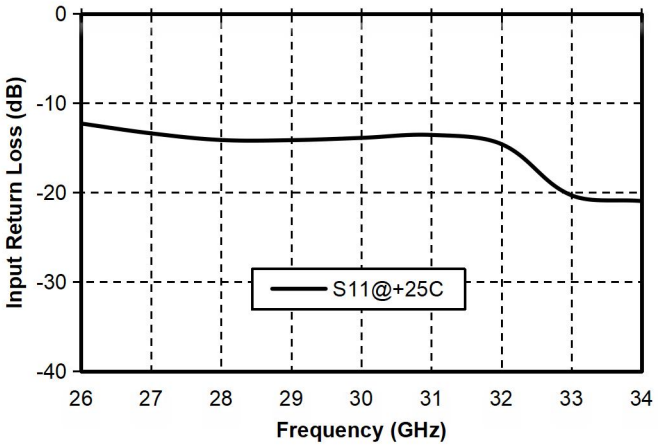
Gain vs. Frequency



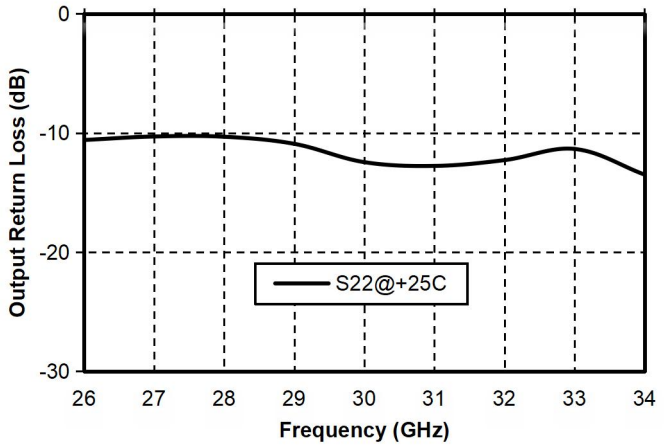
Reverse Isolation vs. Frequency



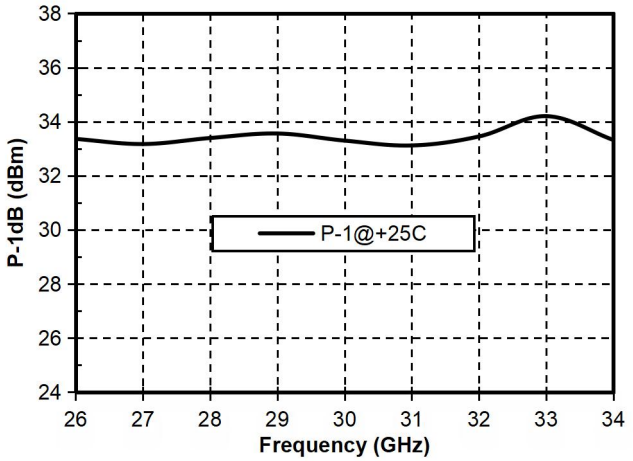
Input Return Loss vs. Frequency



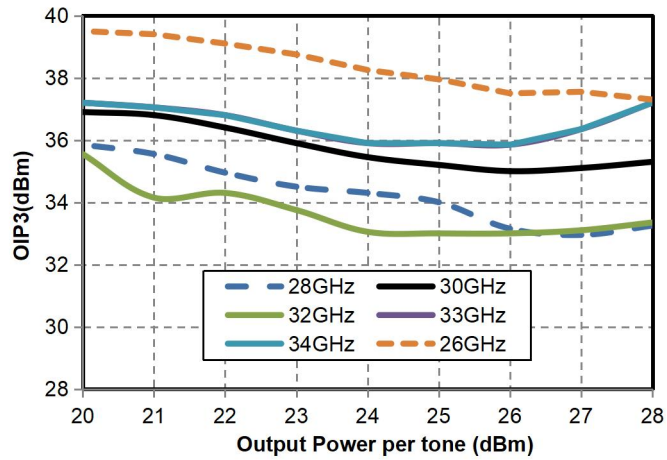
Output Return Loss vs. Frequency



P-1dB vs. Frequency



OIP3 vs. Frequency



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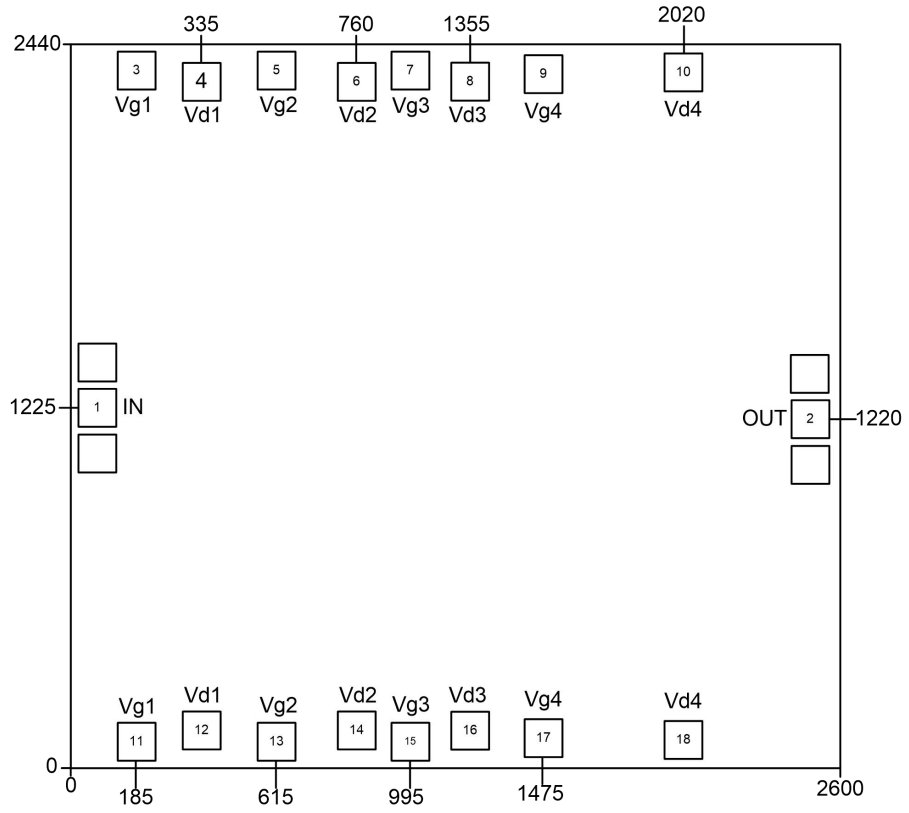
Appearance structure [2]



【 2 】All units in the figure are micrometers

Bonding point definition		
Bonding point number	Function Symbol	Functional Description
1	RF IN	The signal input terminal is connected to a 50 ohm circuit, and no DC blocking capacitor is required.
2	RF OUT	The signal output terminal is connected to a 50 ohm circuit, and no DC blocking capacitor is required.
3, 5, 7, 9, 11, 13, 15, 17	Vg1 ~Vg4	Amplifier drain bias, external 100pF , 1000pF , 4.7uF bypass capacitors are required.
4, 6, 8, 10, 12, 14, 16, 18	Vd1~Vd4	Amplifier drain bias, external 100pF , 1000pF , 4.7uF bypass capacitors are required.
Chip bottom	GND	The bottom of the chip needs to be in good contact with the RF and DC grounds.

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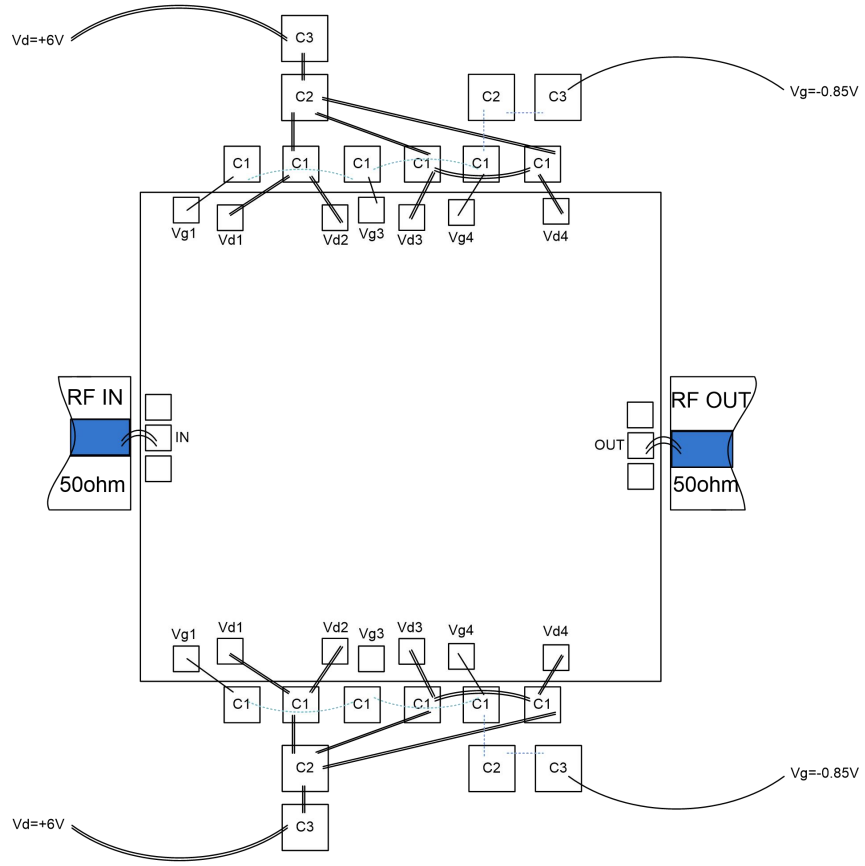
Recommended assembly diagram



raw material	Capacitance, inductance, resistance
C1	100pF
C 2	1000pF
C 3	4.7uF

Notice

- The chip must be stored in an anti-static container and kept in a nitrogen environment.
- Do not attempt to clean the bare die surface using wet chemical methods.
- Please strictly follow the ESD protection requirements to avoid static damage to the bare chip.
- General operation: Please use precision pointed tweezers to pick up bare chips. Avoid touching the chip surface with tools or fingers during operation.
- Rack mounting operation suggestions: AuSn solder eutectic sintering process can be used for bare chip mounting. The mounting surface must be clean and flat.
- Sintering process: It is recommended to use AuSn solder sheets with a gold-tin ratio of 80/20. The working surface temperature reaches 255 ˚C and the tool (vacuum chuck) temperature reaches 265 ˚C . When the high-temperature mixed gas (nitrogen-hydrogen ratio of 90/10) is blown to the chip, the temperature at the top of the tool should be raised to 290 ˚C . Do not let the chip exceed 320 ˚C for more than 20 seconds. The friction time should not exceed 3 seconds.

- Bonding operation suggestions: Use Φ0.025mm (1mil) gold wire for both ball and wedge bonding. Thermosonic bonding temperature is 150 ℃ . The pressure of the wedge bonding knife is 40~50gf for ball bonding and 18~22gf for wedge bonding. Use the smallest possible ultrasonic energy. The bonding starts at the pressure point on the chip and ends at the package (or substrate).